

Final Product Change Notification

 Issue Date:
 20-Jul-2017

 Effective Date:
 18-Oct-2017

201707008F01



QUALITY

Change Category				
Wafer Fab	Assembly Process	S Product Marking	Test Location	Design
Process		C C		C C
Wafer Fab	Assembly	Mechanical Specification	Test Process	Errata
Materials	Materials			
Wafer Fab	Assembly		└─Test	Electrical spec./Test
Location	Location	Packing/Shipping/Labeling	Equipment	coverage

SGTL5000 Copper Wire Qualification

Details of this Change

NXP Semiconductors announces the addition of Palladium Copper (PdCu) wire as a wirebond material for the SGTL5000XNAA3/R2 QFN-EP 32 5x5 package devices. These products are now qualified for assembly at ASECL, Taiwan assembly site. These products were previously assembled with Gold (Au) wire at ASECL, Taiwan assembly site.

NXP Semiconductors also announces the addition of Palladium Copper (PdCu) wire as a wirebond material along with Sumitomo EME-G700LA mold compound and Henkel ATB-125 die attach material for the SGTL5000XNLA3/R2 QFN-EP 20 3x3 package devices. These products are now qualified for assembly at ASECL, Taiwan assembly site. These products were previously assembled with Gold (Au) wire, Hitachi CEL9240HF10AK mold compound, and Nitto 550 die attach material at ASECL, Taiwan assembly site.

Why do we Implement this Change

The transfer from Gold to Palladium Copper wire is required to mitigate against raw material cost increases and for supply assurance. The change to mold compound and die attach material for QFN-EP 20 3x3 package is required to standardize the bill of materials for ASECL QFN package current production.

Identification of Affected Products

Product identification does not change

There is no change to orderable part number. The tracecode marking on the device includes assembly site and datecode. NXP will have traceability by assembly site and datecode.

Product Availability

Sample Information

Samples are available from 21-Jul-2017 Samples available for SGTL5000XNAA3 and SGTL5000XNLA3 with special marking for customer evaluation.

Production

Planned first shipment 19-Oct-2017

Impact

No change to form, fit, or function. Reliability is equivalent or improved.

Disposition of Id Products

Existing inventory will be shipped until depleted

Additional information

Self qualification <u>view online</u> Additional documents <u>view online</u>

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our acknowledgement of this change, conform JEDEC JESD4 D, is expected till 19-Aug-2017.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support</u> <u>Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly

NameFrank LiPositionProduct Engineere mail addressmailto un.li 3 nxp.com sub ect Support

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About N P Semiconductors

NXP Semiconductors N. . (NASDAQ NXP) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, nterface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

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